



Material Content Data Sheet



Sales Product Name		SAB-C165-L25F HA		Issued		29. August 2013		
MA#		MA000098937						
Package		PG-TQFP-100-1		Weight*		702.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.727	1.95	1.95	19540	19540
leadframe	non noble metal	nickel	7440-02-0	77.443	11.02		110236	
	non noble metal	iron	7439-89-6	106.945	15.22	26.24	152231	262467
wire	noble metal	gold	7440-57-5	6.159	0.88	0.88	8767	8767
encapsulation	organic material	carbon black	1333-86-4	1.449	0.21		2062	
	plastics	epoxy resin	-	61.327	8.73		87296	
	inorganic material	silicondioxide	60676-86-0	420.111	59.81	68.75	598007	687365
leadfinish	non noble metal	tin	7440-31-5	6.211	0.88	0.88	8842	8842
plating	noble metal	silver	7440-22-4	6.180	0.88	0.88	8797	8797
glue	plastics	acrylic resin	-	0.593	0.08		844	
	noble metal	silver	7440-22-4	2.373	0.34	0.42	3378	4222
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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